

DIGITAL COMPONENT SENSOR DEVELOPMENT TOOLS

Many of our digital sensor products are available in low power and small form factors. They are suited for wearable and miniature devices that are used to collect and share critical data for health monitoring, fitness, air quality, aerospace, battery powered, and related applications. To increase knowledge sharing and reduce time to market, we have teamed with semiconductor manufacturers to design and provide plug and play tools for Xplained Pro Sensor Hub, MicroChip PicTail, and Digilent Pmod™ based development platforms. In addition, we offer several wireless demo/development tools to help engineers quickly achieve their design objectives with wireless applications. These tools are supported with software/firmware drivers, documentation, and graphic user interfaces to make the development process easy.



WIRELESS DEMO AND DEVELOPMENT KITS



MEAS Environmental Sensor Tag

Humidity, Temperature, Pressure

- 0 100% RH
- 20°C to 85°C
- 300 to 1,200 mbar

Communication Standard 2.4 GHz wireless communication

Application iOS 7.0+ Android™ 4.3+

Туре

Specifications



MEAS Wireless M5600 Series

Pressure

- 50 15K psi
- Type G/S/C

Standard 2.4 GHz wireless communication

iOS 7.0+ Android™ 4.3+



MEAS Wireless U5600 Series

Pressure

- 2 10K psi • Type G/S/C/A

Standard 2.4 GHz wireless communication

iOS 7.0+ Android™ 4.3+

6

MEAS Wireless FX1951

Force

- 0 50 lbf
- Standard 2.4 GHz wireless communication

iOS 7.0+ Android™ 4.3+

PICTAIL PLUS



MEAS HTU21D(F), MS5637, MS8607, TSYS01*

Туре

TE Demo

Specifications

Partner Board

Humidity, Temperature, Pressure

- 0 100% RH
- -20°C to 85°C
- 300 to 1,200 mbar

PicTail Plus

Microchip Explorer 16

^{*}Temperature System Sensor (TSYS) Series

DIGITAL COMPONENT SENSOR DEVELOPMENT TOOLS



PERIPHERAL MODULES

Digilent Pmod™





MEAS MS5637

• 10 to 2,000 mbar

• -40 to 85°C

• 15 to 36 V

±2 mbar

I²C

Pressure









MEAS HTU21D(F	į

Туре Humidity

Specifications • 0 to 100% RH • -40 to 125°C

• 3.3 to 5.5 V

Accuracy ±3% RH

Comm. Interface

Board Connections

Compatibility

compatible with Digilent Pmod™

6 x 2 x 0.1" header input & output Development systems

connections

120

6 x 2 x 0.1" header input & output

Development systems compatible with Digilent Pmod™ connections

MEAS MS8607

Pressure. Temperature, Humidity

• 10 to 2,000 mmar • -40 to 85°C

• 0 to 100% RH • 1.5 to 3.6 V

±3% RH, ±2 mbar, ±1.0°C

120

6 x 2 x 0.1" header input & output

Development systems compatible with Digilent Pmod™

connections

MEAS TSYSO1*

Temperature

• -40 to 125°C

• 2.2 to 3.6 V

±0.1°C

6 x 2 x 0.1" header input & output

Development systems

compatible with Digilent Pmod™ connections

MEAS TSYSO2D*

Temperature

• -40 to 125°C

• 1.5 to 3.6 V

±0.2°C

1²C

6 x 2 x 0.1" header input & output

Development systems compatible with Digilent Pmod™ connections

MEAS KMA36(A)

Angular Position

• 0 to 360°

• -25 to 85°C • 2.9 to 6.0 V

±0.1°

120

6 x 2 x 0.1" header input & output

Development systems compatible with Digilent Pmod™ connections

WING BOARDS















MEAS HTU21D(F)

Туре

Specifications

• 3.3 to 5.5 V

Accuracy

Comm. Interface

Connections Compatibility Humidity

• 0 to 100% RH

• -40°C to 125°C

±3% RH

Board

10 x 2 x 0.1" header input & output

Configured to operate with the Xplained Pro development platform

MEAS MS5637

Pressure

• 10 to 2,000 mbar

• -40 to 85°C • 1.5 to 3.6 V

±2 mBar

10 x 2 x 0.1" header input & output

Configured to operate with the Xplained Pro development platform

MEAS MS8607

Pressure. Temperature, Humidity

• 10 to 2,000 mbar

• -40°C to 85°C

• 0 to 100% RH

• 1.5 to 3.6 V

±3% RH, ±2 mBar, ±1.0°C

10 x 2 x 0.1" header input & output

Configured to operate with the Xplained Pro development platform

MEAS TSYSO1*

Temperature

• -40°C to 125°C

• 2.2 to 3.6 V

±0.1°C

10 x 2 x 0.1" header input & output

Configured to operate with the Xplained Pro development platform

• 1.5 to 3.6 V

MEAS KMA36(A)

Angular Position

• 0 to 360° • -25°C to 85°C

• 2.9 to 6.0 V

±0.1°

10 x 2 x 0.1" header input & output

Configured to operate

DRIVERS





FPGA Bare Metal -Linux® / Android™ ANSI C Coding

PIC24x Family

MEAS HTU21D(F)

SAMD2x Microchip



MEAS MS5637

SAMD2x Microchip PIC24x Family FPGA Bare Metal -Linux® / Android™

ANSI C Coding



MEAS MS8607

SAMD2x Microchip PIC24x Family FPGA Bare Metal -Linux® / Android™

ANSI C Coding



MEAS TSYSO1*

SAMD2x Microchip PIC24x Family FPGA Bare Metal -Linux® / Android™

ANSI C Coding



Temperature

• -40°C to 125°C

±0.2°C

10 x 2 x 0.1" header input & output

Configured to operate with the Xplained Pro development platform

with the Xplained Pro development platform



SAMD2x Microchip PIC24x Family FPGA Bare Metal -Linux / Android™

ANSI C Coding



MEAS KMA36(A)

SAMD2x Microchip PIC24x Family FPGA Bare Metal -Linux® / Android™

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ANSI C Coding



Type

Language

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

TE Connectivity:

<u>DPP901A000</u> <u>DPP901Z000</u> <u>DPP202Z000</u> <u>DPP201A000</u> <u>DPP401A000</u> <u>DPP201Z000</u> <u>DPP202A000</u> <u>DPP101A000</u> <u>DPP401Z000</u> <u>DPP402Z000</u>